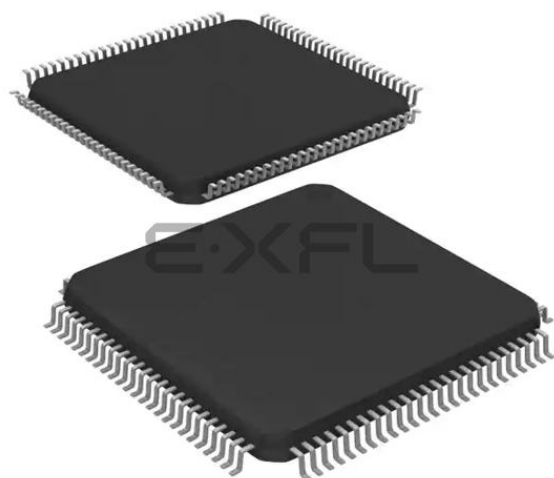




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Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I ² C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	86
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg880f1024g-e-qfp100r

1 Ordering Information

Table 1.1 (p. 2) shows the available EFM32GG880 devices.

Table 1.1. Ordering Information

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (°C)	Package
EFM32GG880F512G-E-QFP100	512	128	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32GG880F1024G-E-QFP100	1024	128	48	1.98 - 3.8	-40 - 85	LQFP100

Adding the suffix 'R' to the part number (e.g. EFM32GG880F512G-E-QFP100R) denotes tape and reel.

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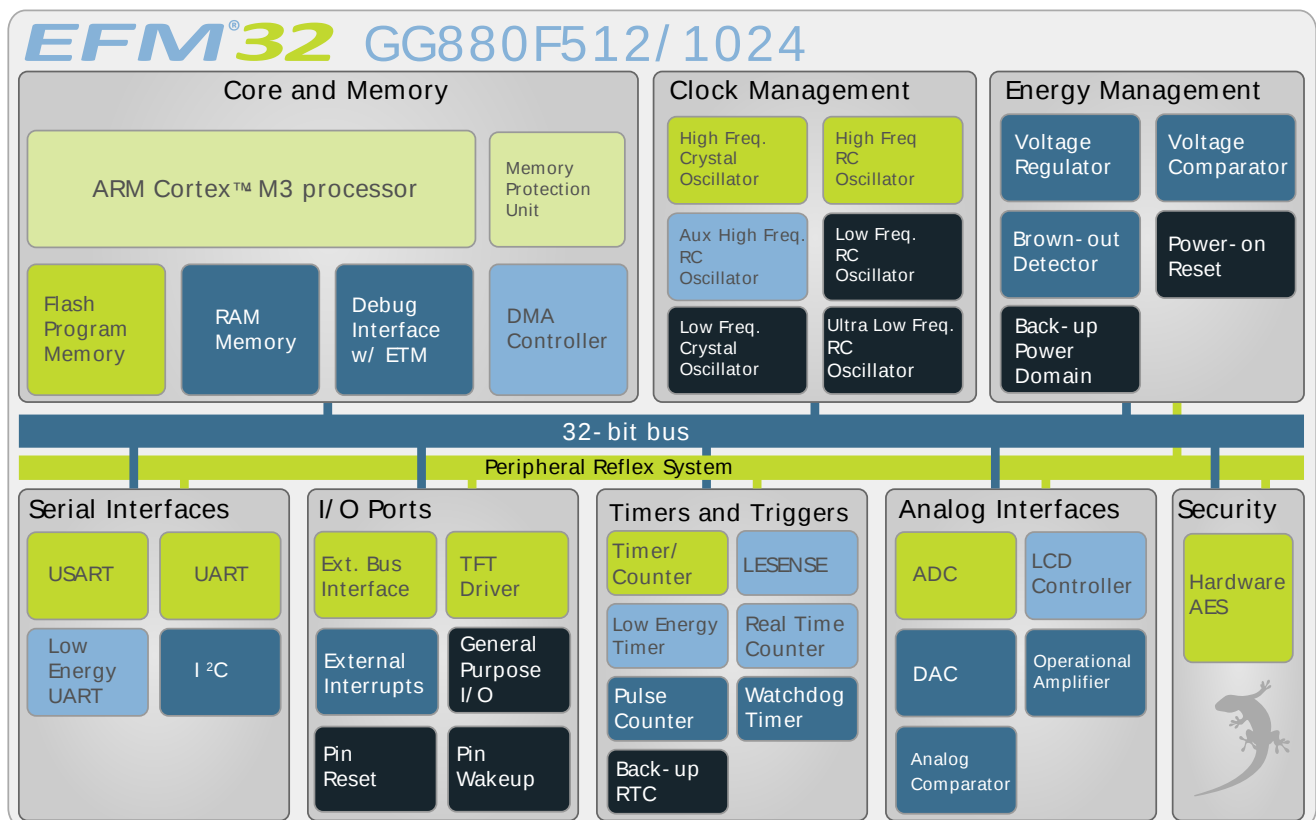
2 System Summary

2.1 System Introduction

The EFM32 MCUs are the world's most energy friendly microcontrollers. With a unique combination of the powerful 32-bit ARM Cortex-M3, innovative low energy techniques, short wake-up time from energy saving modes, and a wide selection of peripherals, the EFM32GG microcontroller is well suited for any battery operated application as well as other systems requiring high performance and low-energy consumption. This section gives a short introduction to each of the modules in general terms and also shows a summary of the configuration for the EFM32GG880 devices. For a complete feature set and in-depth information on the modules, the reader is referred to the *EFM32GG Reference Manual*.

A block diagram of the EFM32GG880 is shown in Figure 2.1 (p. 3) .

Figure 2.1. Block Diagram



2.1.1 ARM Cortex-M3 Core

The ARM Cortex-M3 includes a 32-bit RISC processor which can achieve as much as 1.25 Dhrystone MIPS/MHz. A Memory Protection Unit with support for up to 8 memory segments is included, as well as a Wake-up Interrupt Controller handling interrupts triggered while the CPU is asleep. The EFM32 implementation of the Cortex-M3 is described in detail in *EFM32 Cortex-M3 Reference Manual*.

2.1.2 Debug Interface (DBG)

This device includes hardware debug support through a 2-pin serial-wire debug interface and an Embedded Trace Module (ETM) for data/instruction tracing. In addition there is also a 1-wire Serial Wire Viewer pin which can be used to output profiling information, data trace and software-generated messages.

2.1.19 Backup Real Time Counter (BURTC)

The Backup Real Time Counter (BURTC) contains a 32-bit counter and is clocked either by a 32.768 kHz crystal oscillator, a 32.768 kHz RC oscillator or a 1 kHz ULFRCO. The BURTC is available in all Energy Modes and it can also run in backup mode, making it operational even if the main power should drain out.

2.1.20 Low Energy Timer (LETIMER)

The unique LETIMER[™], the Low Energy Timer, is a 16-bit timer that is available in energy mode EM2 in addition to EM1 and EM0. Because of this, it can be used for timing and output generation when most of the device is powered down, allowing simple tasks to be performed while the power consumption of the system is kept at an absolute minimum. The LETIMER can be used to output a variety of waveforms with minimal software intervention. It is also connected to the Real Time Counter (RTC), and can be configured to start counting on compare matches from the RTC.

2.1.21 Pulse Counter (PCNT)

The Pulse Counter (PCNT) can be used for counting pulses on a single input or to decode quadrature encoded inputs. It runs off either the internal LFACLK or the PCNTn_S0IN pin as external clock source. The module may operate in energy mode EM0 - EM3.

2.1.22 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs can either be one of the selectable internal references or from external pins. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

2.1.23 Voltage Comparator (VCMP)

The Voltage Supply Comparator is used to monitor the supply voltage from software. An interrupt can be generated when the supply falls below or rises above a programmable threshold. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

2.1.24 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture, with a resolution of up to 12 bits at up to one million samples per second. The integrated input mux can select inputs from 8 external pins and 6 internal signals.

2.1.25 Digital to Analog Converter (DAC)

The Digital to Analog Converter (DAC) can convert a digital value to an analog output voltage. The DAC is fully differential rail-to-rail, with 12-bit resolution. It has two single ended output buffers which can be combined into one differential output. The DAC may be used for a number of different applications such as sensor interfaces or sound output.

2.1.26 Operational Amplifier (OPAMP)

The EFM32GG880 features 3 Operational Amplifiers. The Operational Amplifier is a versatile general purpose amplifier with rail-to-rail differential input and rail-to-rail single ended output. The input can be set to pin, DAC or OPAMP, whereas the output can be pin, OPAMP or ADC. The current is programmable and the OPAMP has various internal configurations such as unity gain, programmable gain using internal resistors etc.

2.1.27 Low Energy Sensor Interface (LESENSE)

The Low Energy Sensor Interface (LESENSE[™]), is a highly configurable sensor interface with support for up to 16 individually configurable sensors. By controlling the analog comparators and DAC, LESENSE

is capable of supporting a wide range of sensors and measurement schemes, and can for instance measure LC sensors, resistive sensors and capacitive sensors. LESENSE also includes a programmable FSM which enables simple processing of measurement results without CPU intervention. LESENSE is available in energy mode EM2, in addition to EM0 and EM1, making it ideal for sensor monitoring in applications with a strict energy budget.

2.1.28 Backup Power Domain

The backup power domain is a separate power domain containing a Backup Real Time Counter, BURTC, and a set of retention registers, available in all energy modes. This power domain can be configured to automatically change power source to a backup battery when the main power drains out. The backup power domain enables the EFM32GG880 to keep track of time and retain data, even if the main power source should drain out.

2.1.29 Advanced Encryption Standard Accelerator (AES)

The AES accelerator performs AES encryption and decryption with 128-bit or 256-bit keys. Encrypting or decrypting one 128-bit data block takes 52 HFCORECLK cycles with 128-bit keys and 75 HFCORECLK cycles with 256-bit keys. The AES module is an AHB slave which enables efficient access to the data and key registers. All write accesses to the AES module must be 32-bit operations, i.e. 8- or 16-bit operations are not supported.

2.1.30 General Purpose Input/Output (GPIO)

In the EFM32GG880, there are 85 General Purpose Input/Output (GPIO) pins, which are divided into ports with up to 16 pins each. These pins can individually be configured as either an output or input. More advanced configurations like open-drain, filtering and drive strength can also be configured individually for the pins. The GPIO pins can also be overridden by peripheral pin connections, like Timer PWM outputs or USART communication, which can be routed to several locations on the device. The GPIO supports up to 16 asynchronous external pin interrupts, which enables interrupts from any pin on the device. Also, the input value of a pin can be routed through the Peripheral Reflex System to other peripherals.

2.1.31 Liquid Crystal Display Driver (LCD)

The LCD driver is capable of driving a segmented LCD display with up to 8x36 segments. A voltage boost function enables it to provide the LCD display with higher voltage than the supply voltage for the device. In addition, an animation feature can run custom animations on the LCD display without any CPU intervention. The LCD driver can also remain active even in Energy Mode 2 and provides a Frame Counter interrupt that can wake-up the device on a regular basis for updating data.

2.2 Configuration Summary

The features of the EFM32GG880 is a subset of the feature set described in the EFM32GG Reference Manual. Table 2.1 (p. 7) describes device specific implementation of the features.

Table 2.1. Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA

3.8 General Purpose Input Output

Table 3.7. GPIO

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V _{IOIL}	Input low voltage				0.30V _{DD}	V
V _{IOIH}	Input high voltage		0.70V _{DD}			V
V _{IOOH}	Output high voltage (Production test condition = 3.0V, DRIVEMODE = STANDARD)	Sourcing 0.1 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = LOWEST		0.80V _{DD}		V
		Sourcing 0.1 mA, V _{DD} =3.0 V, GPIO_Px_CTRL DRIVEMODE = LOWEST		0.90V _{DD}		V
		Sourcing 1 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = LOW		0.85V _{DD}		V
		Sourcing 1 mA, V _{DD} =3.0 V, GPIO_Px_CTRL DRIVEMODE = LOW		0.90V _{DD}		V
		Sourcing 6 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	0.75V _{DD}			V
		Sourcing 6 mA, V _{DD} =3.0 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	0.85V _{DD}			V
		Sourcing 20 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = HIGH	0.60V _{DD}			V
		Sourcing 20 mA, V _{DD} =3.0 V, GPIO_Px_CTRL DRIVEMODE = HIGH	0.80V _{DD}			V
V _{IOOL}	Output low voltage (Production test condition = 3.0V, DRIVEMODE = STANDARD)	Sinking 0.1 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = LOWEST		0.20V _{DD}		V
		Sinking 0.1 mA, V _{DD} =3.0 V, GPIO_Px_CTRL DRIVEMODE = LOWEST		0.10V _{DD}		V
		Sinking 1 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = LOW		0.10V _{DD}		V
		Sinking 1 mA, V _{DD} =3.0 V, GPIO_Px_CTRL DRIVEMODE = LOW		0.05V _{DD}		V
		Sinking 6 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = STANDARD			0.30V _{DD}	V
		Sinking 6 mA, V _{DD} =3.0 V, GPIO_Px_CTRL DRIVEMODE = STANDARD			0.20V _{DD}	V
		Sinking 20 mA, V _{DD} =1.98 V, GPIO_Px_CTRL DRIVEMODE = HIGH			0.35V _{DD}	V

Symbol	Parameter	Condition	Min	Typ	Max	Unit
		500 kSamples/s, 12 bit, differential, internal 2.5V reference		58		dB
		500 kSamples/s, 12 bit, differential, V_{DD} reference		59		dB
SNDR _{DAC}	Signal to Noise-pulse Distortion Ratio (SNDR)	500 kSamples/s, 12 bit, single ended, internal 1.25V reference		57		dB
		500 kSamples/s, 12 bit, single ended, internal 2.5V reference		54		dB
		500 kSamples/s, 12 bit, differential, internal 1.25V reference		56		dB
		500 kSamples/s, 12 bit, differential, internal 2.5V reference		53		dB
		500 kSamples/s, 12 bit, differential, V_{DD} reference		55		dB
SFDR _{DAC}	Spurious-Free Dynamic Range(SFDR)	500 kSamples/s, 12 bit, single ended, internal 1.25V reference		62		dBc
		500 kSamples/s, 12 bit, single ended, internal 2.5V reference		56		dBc
		500 kSamples/s, 12 bit, differential, internal 1.25V reference		61		dBc
		500 kSamples/s, 12 bit, differential, internal 2.5V reference		55		dBc
		500 kSamples/s, 12 bit, differential, V_{DD} reference		60		dBc
V _{DACOFFSET}	Offset voltage	After calibration, single ended		2	12	mV
		After calibration, differential		2		mV
DNL _{DAC}	Differential non-linearity			±1		LSB
INL _{DAC}	Integral non-linearity			±5		LSB
MC _{DAC}	No missing codes			12		bits

¹ Measured with a static input code and no loading on the output.

3.12 Operational Amplifier (OPAMP)

The electrical characteristics for the Operational Amplifiers are based on simulations.

Table 3.16. OPAMP

Symbol	Parameter	Condition	Min	Typ	Max	Unit
I _{OPAMP}	Active Current	(OPA2)BIASPROG=0xF, (OPA2)HALFBIAS=0x0, Unity Gain		350	405	μA
		(OPA2)BIASPROG=0x7, (OPA2)HALFBIAS=0x1, Unity Gain		95	115	μA

Symbol	Parameter	Condition	Min	Typ	Max	Unit
		(OPA2)BIASPROG=0x0, (OPA2)HALFBIAS=0x1, Unity Gain		13	17	μA
G _{OL}	Open Loop Gain	(OPA2)BIASPROG=0xF, (OPA2)HALFBIAS=0x0		101		dB
		(OPA2)BIASPROG=0x7, (OPA2)HALFBIAS=0x1		98		dB
		(OPA2)BIASPROG=0x0, (OPA2)HALFBIAS=0x1		91		dB
GBW _{OPAMP}	Gain Bandwidth Product	(OPA2)BIASPROG=0xF, (OPA2)HALFBIAS=0x0		6.1		MHz
		(OPA2)BIASPROG=0x7, (OPA2)HALFBIAS=0x1		1.8		MHz
		(OPA2)BIASPROG=0x0, (OPA2)HALFBIAS=0x1		0.25		MHz
PM _{OPAMP}	Phase Margin	(OPA2)BIASPROG=0xF, (OPA2)HALFBIAS=0x0, C _L =75 pF		64		°
		(OPA2)BIASPROG=0x7, (OPA2)HALFBIAS=0x1, C _L =75 pF		58		°
		(OPA2)BIASPROG=0x0, (OPA2)HALFBIAS=0x1, C _L =75 pF		58		°
R _{INPUT}	Input Resistance			100		Mohm
R _{LOAD}	Load Resistance		200			Ohm
I _{LOAD_DC}	DC Load Current				11	mA
V _{INPUT}	Input Voltage	OPAxHCMDIS=0	V _{SS}		V _{DD}	V
		OPAxHCMDIS=1	V _{SS}		V _{DD} -1.2	V
V _{OUTPUT}	Output Voltage		V _{SS}		V _{DD}	V
V _{OFFSET}	Input Offset Voltage	Unity Gain, V _{SS} <V _{in} <V _{DD} , OPAxHCMDIS=0	-13	0	11	mV
		Unity Gain, V _{SS} <V _{in} <V _{DD} -1.2, OPAxHCMDIS=1		1		mV
V _{OFFSET_DRIFT}	Input Offset Voltage Drift				0.02	mV/°C
SR _{OPAMP}	Slew Rate	(OPA2)BIASPROG=0xF, (OPA2)HALFBIAS=0x0		3.2		V/μs
		(OPA2)BIASPROG=0x7, (OPA2)HALFBIAS=0x1		0.8		V/μs
		(OPA2)BIASPROG=0x0, (OPA2)HALFBIAS=0x1		0.1		V/μs
N _{OPAMP}	Voltage Noise	V _{out} =1V, RESSEL=0, 0.1 Hz<f<10 kHz, OPAx- HCMDIS=0		101		μV _{RMS}
		V _{out} =1V, RESSEL=0, 0.1 Hz<f<10 kHz, OPAx- HCMDIS=1		141		μV _{RMS}

Symbol	Parameter	Condition	Min	Typ	Max	Unit
		$V_{out}=1V$, RESSEL=0, 0.1 Hz< f <1 MHz, OPAXHCMDIS=0		196		μV_{RMS}
		$V_{out}=1V$, RESSEL=0, 0.1 Hz< f <1 MHz, OPAXHCMDIS=1		229		μV_{RMS}
		RESSEL=7, 0.1 Hz< f <10 kHz, OPAXHCMDIS=0		1230		μV_{RMS}
		RESSEL=7, 0.1 Hz< f <10 kHz, OPAXHCMDIS=1		2130		μV_{RMS}
		RESSEL=7, 0.1 Hz< f <1 MHz, OPAXHCMDIS=0		1630		μV_{RMS}
		RESSEL=7, 0.1 Hz< f <1 MHz, OPAXHCMDIS=1		2590		μV_{RMS}

Figure 3.25. OPAMP Common Mode Rejection Ratio

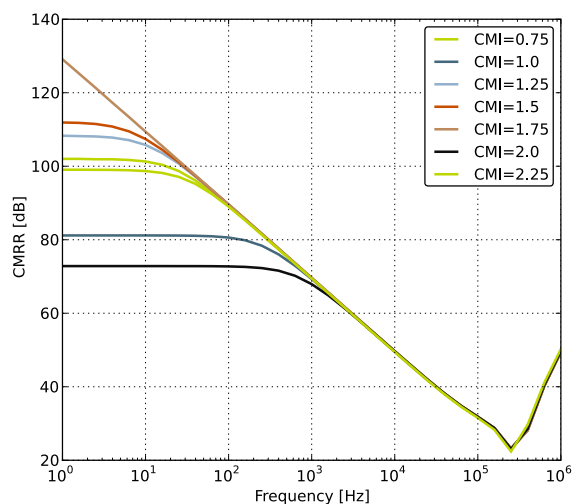


Figure 3.26. OPAMP Positive Power Supply Rejection Ratio

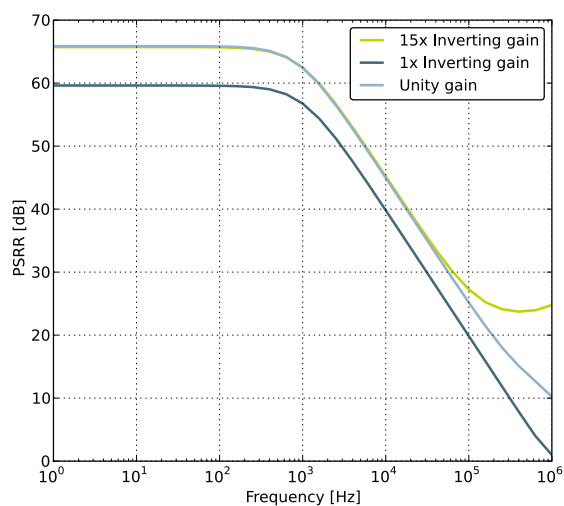


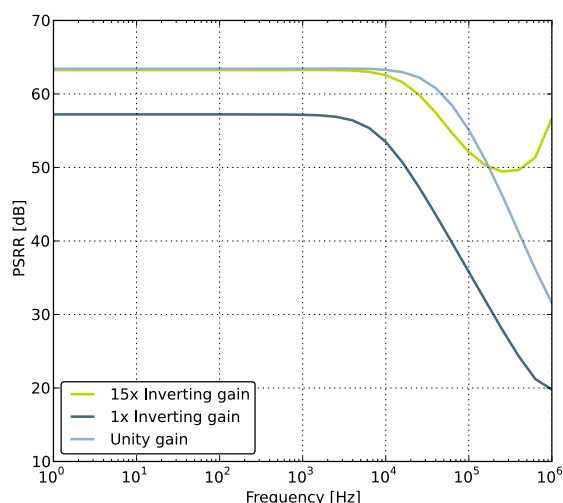
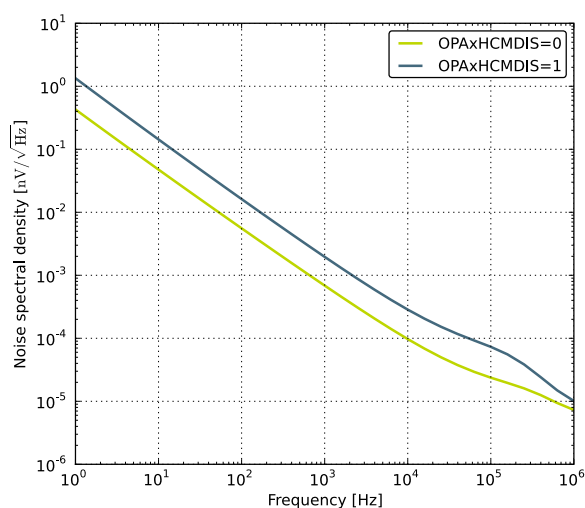
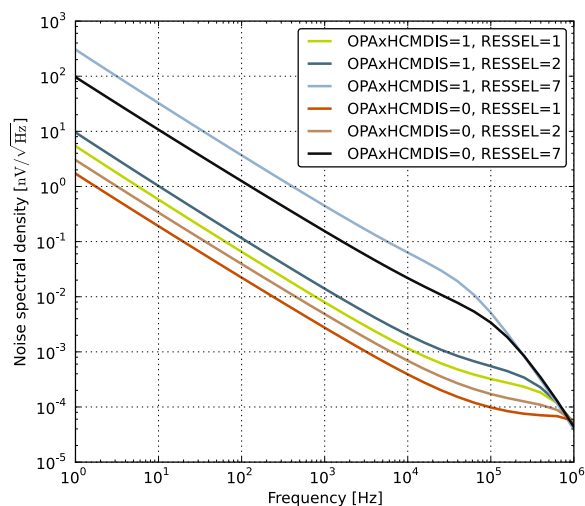
Figure 3.27. OPAMP Negative Power Supply Rejection Ratio**Figure 3.28. OPAMP Voltage Noise Spectral Density (Unity Gain) $V_{out}=1V$** **Figure 3.29. OPAMP Voltage Noise Spectral Density (Non-Unity Gain)**

Table 3.19. EBI Write Enable Timing

Symbol	Parameter	Min	Typ	Max	Unit
$t_{OH_WEn}^{1\ 2\ 3\ 4}$	Output hold time, from trailing EBI_WEn/ EBI_NANDWEn edge to EBI_AD, EBI_A, EBI_CSn, EBI_BLn invalid	$-6.00 + (WRHOLD * t_{HFCORECLK})$			ns
$t_{OSU_WEn}^{1\ 2\ 3\ 4\ 5}$	Output setup time, from EBI_AD, EBI_A, EBI_CSn, EBI_BLn valid to leading EBI_WEn/ EBI_NANDWEn edge	$-14.00 + (WRSETUP * t_{HFCORECLK})$			ns
$t_{WIDTH_WEn}^{1\ 2\ 3\ 4\ 5}$	EBI_WEn/EBI_NANDWEn pulse width	$-7.00 + ((WRSTRB + 1) * t_{HFCORECLK})$			ns

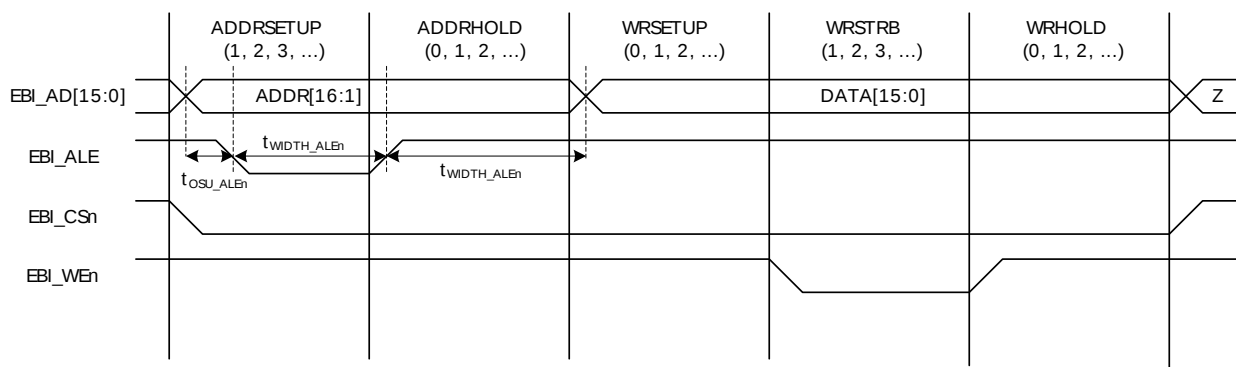
¹Applies for all addressing modes (figure only shows D16 addressing mode)

²Applies for both EBI_WEn and EBI_NANWEn (figure only shows EBI_WEn)

³Applies for all polarities (figure only shows active low signals)

⁴Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

⁵ The figure shows the timing for the case that the half strobe length functionality is not used, i.e. HALFWE=0. The leading edge of EBI_WEn can be moved to the right by setting HALFWE=1. This decreases the length of t_{WIDTH_WEn} and increases the length of t_{OSU_WEn} by $1/2 * t_{HFCLKNODIV}$.

Figure 3.32. EBI Address Latch Enable Related Output Timing**Table 3.20. EBI Address Latch Enable Related Output Timing**

Symbol	Parameter	Min	Typ	Max	Unit
$t_{OH_ALEn}^{1\ 2\ 3\ 4}$	Output hold time, from trailing EBI_ALE edge to EBI_AD invalid	$-6.00 + (ADDRHOLD^5 * t_{HFCORECLK})$			ns
$t_{OSU_ALEn}^{1\ 2\ 4}$	Output setup time, from EBI_AD valid to leading EBI_ALE edge	$-13.00 + (0 * t_{HFCORECLK})$			ns
$t_{WIDTH_ALEn}^{1\ 2\ 3\ 4}$	EBI_ALEn pulse width	$-7.00 + (ADDRSETUP + 1) * t_{HFCORECLK}$			ns

¹Applies to addressing modes D8A24ALE and D16A16ALE (figure only shows D16A16ALE)

²Applies for all polarities (figure only shows active low signals)

³ The figure shows the timing for the case that the half strobe length functionality is not used, i.e. HALFALE=0. The trailing edge of EBI_ALE can be moved to the left by setting HALFALE=1. This decreases the length of t_{WIDTH_ALEn} and increases the length of t_{OH_ALEn} by $t_{HFCORECLK} - 1/2 * t_{HFCLKNODIV}$.

⁴Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

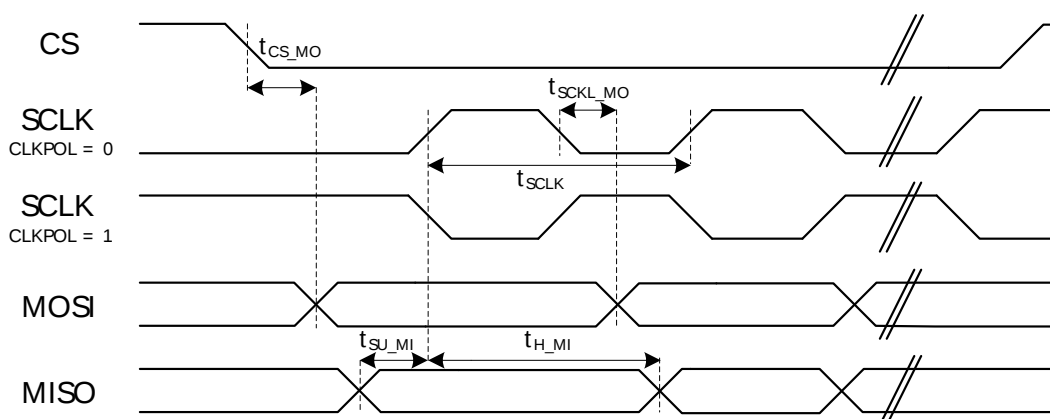
⁵Figure only shows a write operation. For a multiplexed read operation the address hold time is controlled via the RDSETUP state instead of via the ADDRHOLD state.

Table 3.27. I2C Fast-mode Plus (Fm+)

Symbol	Parameter	Min	Typ	Max	Unit
f_{SCL}	SCL clock frequency	0		1000 ¹	kHz
t_{LOW}	SCL clock low time	0.5			μ s
t_{HIGH}	SCL clock high time	0.26			μ s
$t_{SU,DAT}$	SDA set-up time	50			ns
$t_{HD,DAT}$	SDA hold time	8			ns
$t_{SU,STA}$	Repeated START condition set-up time	0.26			μ s
$t_{HD,STA}$	(Repeated) START condition hold time	0.26			μ s
$t_{SU,STO}$	STOP condition set-up time	0.26			μ s
t_{BUF}	Bus free time between a STOP and START condition	0.5			μ s

¹For the minimum HPERCLK frequency required in Fast-mode Plus, see the I2C chapter in the EFM32GG Reference Manual.

3.18 USART SPI

Figure 3.36. SPI Master Timing**Table 3.28. SPI Master Timing**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$t_{SCLK}^{1,2}$	SCLK period		$2 * t_{HFER-CLK}$			ns
$t_{CS_MO}^{1,2}$	CS to MOSI		-2.00		1.00	ns
$t_{SCLK_MO}^{1,2}$	SCLK to MOSI		-4.00		3.00	ns
$t_{SU_MI}^{1,2}$	MISO setup time	IOVDD = 1.98 V	36.00			ns
		IOVDD = 3.0 V	29.00			ns
$t_{H_MI}^{1,2}$	MISO hold time		-4.00			ns

¹Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)

²Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

4 Pinout and Package

Note

Please refer to the application note "AN0002 EFM32 Hardware Design Considerations" for guidelines on designing Printed Circuit Boards (PCB's) for the EFM32GG880.

4.1 Pinout

The EFM32GG880 pinout is shown in Figure 4.1 (p. 54) and Table 4.1 (p. 54). Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

Figure 4.1. EFM32GG880 Pinout (top view, not to scale)

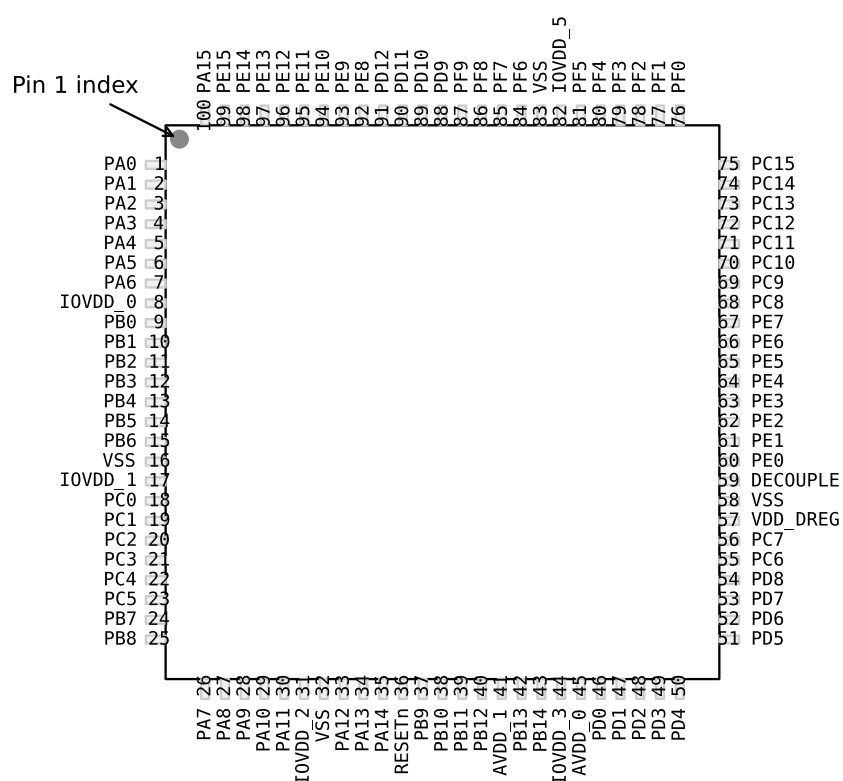


Table 4.1. Device Pinout

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
1	PA0	LCD_SEG13	EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	I2C0_SDA #0 LEU0_RX #4	PRS_CH0 #0 GPIO_EM4WU0
2	PA1	LCD_SEG14	EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2	LCD_SEG15	EBI_AD11 #0/1/2	TIM0_CC2 #0/1		CMU_CLK0 #0

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP1_CH4	PC12							Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13							Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14							Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15							Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3	PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2							Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3							Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 / OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 / OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1ALT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15	PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.
EBI_A06	PC7	PC7	PC7					External Bus Interface (EBI) address output pin 06.
EBI_A07	PE0	PE0	PE0					External Bus Interface (EBI) address output pin 07.
EBI_A08	PE1	PE1	PE1					External Bus Interface (EBI) address output pin 08.
EBI_A09	PE2	PC9	PC9					External Bus Interface (EBI) address output pin 09.
EBI_A10	PE3	PC10	PC10					External Bus Interface (EBI) address output pin 10.
EBI_A11	PE4	PE4	PE4					External Bus Interface (EBI) address output pin 11.
EBI_A12	PE5	PE5	PE5					External Bus Interface (EBI) address output pin 12.
EBI_A13	PE6	PE6	PE6					External Bus Interface (EBI) address output pin 13.
EBI_A14	PE7	PE7	PE7					External Bus Interface (EBI) address output pin 14.
EBI_A15	PC8	PC8	PC8					External Bus Interface (EBI) address output pin 15.
EBI_A16	PB0	PB0	PB0					External Bus Interface (EBI) address output pin 16.
EBI_A17	PB1	PB1	PB1					External Bus Interface (EBI) address output pin 17.
EBI_A18	PB2	PB2	PB2					External Bus Interface (EBI) address output pin 18.
EBI_A19	PB3	PB3	PB3					External Bus Interface (EBI) address output pin 19.
EBI_A20	PB4	PB4	PB4					External Bus Interface (EBI) address output pin 20.
EBI_A21	PB5	PB5	PB5					External Bus Interface (EBI) address output pin 21.
EBI_A22	PB6	PB6	PB6					External Bus Interface (EBI) address output pin 22.
EBI_A23	PC0	PC0	PC0					External Bus Interface (EBI) address output pin 23.
EBI_A24	PC1	PC1	PC1					External Bus Interface (EBI) address output pin 24.
EBI_A25	PC2	PC2	PC2					External Bus Interface (EBI) address output pin 25.
EBI_A26	PC4	PC4	PC4					External Bus Interface (EBI) address output pin 26.
EBI_A27	PD2	PD2	PD2					External Bus Interface (EBI) address output pin 27.
EBI_AD00	PE8	PE8	PE8					External Bus Interface (EBI) address and data input / output pin 00.
EBI_AD01	PE9	PE9	PE9					External Bus Interface (EBI) address and data input / output pin 01.
EBI_AD02	PE10	PE10	PE10					External Bus Interface (EBI) address and data input / output pin 02.
EBI_AD03	PE11	PE11	PE11					External Bus Interface (EBI) address and data input / output pin 03.
EBI_AD04	PE12	PE12	PE12					External Bus Interface (EBI) address and data input / output pin 04.
EBI_AD05	PE13	PE13	PE13					External Bus Interface (EBI) address and data input / output pin 05.
EBI_AD06	PE14	PE14	PE14					External Bus Interface (EBI) address and data input / output pin 06.
EBI_AD07	PE15	PE15	PE15					External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15	PA15	PA15					External Bus Interface (EBI) address and data input / output pin 08.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LES_ALTEX3	PA4							LESENSE alternate exit output 3.
LES_ALTEX4	PA5							LESENSE alternate exit output 4.
LES_ALTEX5	PE11							LESENSE alternate exit output 5.
LES_ALTEX6	PE12							LESENSE alternate exit output 6.
LES_ALTEX7	PE13							LESENSE alternate exit output 7.
LES_CH0	PC0							LESENSE channel 0.
LES_CH1	PC1							LESENSE channel 1.
LES_CH2	PC2							LESENSE channel 2.
LES_CH3	PC3							LESENSE channel 3.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH8	PC8							LESENSE channel 8.
LES_CH9	PC9							LESENSE channel 9.
LES_CH10	PC10							LESENSE channel 10.
LES_CH11	PC11							LESENSE channel 11.
LES_CH12	PC12							LESENSE channel 12.
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1	PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4						Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1	PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0	PF6	PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.

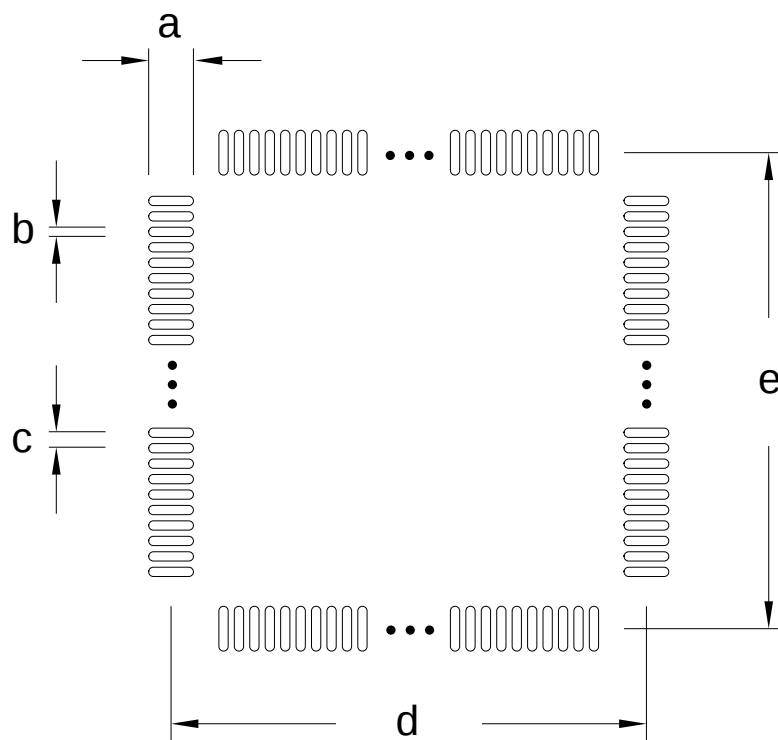
Table 4.4. LQFP100 (Dimensions in mm)

		SYMBOL	MIN	NOM	MAX
total thickness		A	--	--	1.6
stand off		A1	0.05	--	0.15
mold thickness		A2	1.35	1.4	1.45
lead width (plating)		b	0.17	0.2	0.27
lead width		b1	0.17	--	0.23
L/F thickness (plating)		c	0.09	--	0.2
lead thickness		c1	0.09	--	0.16
body size	x	D	16 BSC		
	y	E	16 BSC		
	x	D1	14 BSC		
	y	E1	14 BSC		
lead pitch		e	0.5 BSC		
		L	0.45	0.6	0.75
footprint		L1	1 REF		
		θ	0°	3.5°	7°
		θ1	0°	--	--
		θ2	11°	12°	13°
		θ3	11°	12°	13°
		R1	0.08	--	--
		R1	0.08	--	0.2
		S	0.2	--	--
package edge tolerance		aaa	0.2		
lead edge tolerance		bbb	0.2		
coplanarity		ccc	0.08		
lead offset		ddd	0.08		
mold flatness		eee	0.05		

The LQFP100 Package uses Nickel-Palladium-Gold preplated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see:
<http://www.silabs.com/support/quality/pages/default.aspx>

Figure 5.3. LQFP100 PCB Stencil Design**Table 5.3. QFP100 PCB Stencil Design Dimensions (Dimensions in mm)**

Symbol	Dim. (mm)
a	1.35
b	0.20
c	0.50
d	15.40
e	15.40

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Figure 4.3 (p. 67) .

5.2 Soldering Information

The latest IPC/JEDEC J-STD-020 recommendations for Pb-Free reflow soldering should be followed.

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